# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers  

**Marketing Name / Model**  
[List multiple models if applicable.]  
HP Pro 3015 Microtower Business PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>2</td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>2</td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

1.3 Markings for plastic parts greater than 25 grams

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Oak EMEA Main Bezel</td>
<td>Main front bezel piece</td>
<td>150</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>Oak EMEA Bezel Frame</td>
<td>Front bezel frame</td>
<td>194</td>
<td>&gt;ABS&lt;</td>
<td></td>
</tr>
<tr>
<td>System Fan Frame</td>
<td>Fan Frame</td>
<td>47</td>
<td>&gt;PBT-GF30-FR(17)&lt;</td>
<td></td>
</tr>
<tr>
<td>CPU Heatsink Fan Frame</td>
<td>Fan Frame</td>
<td>37</td>
<td>&gt;PBT-GF30-FR(17)&lt;</td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. SYSTEM BOARD

1.1 Remove the access panel:

a) Remove the screw that secure the access panel to the computer chassis. (see Figure 1 below)

b) Pull the panel off the unit. (see Figure 2 below)

1.2 Disconnect the data cables from the board.(see Figure 3-8 below)

a) Disconnect the CPU cable and ATX cables from the board.

b) Disconnect the ODD cable and HDD cable from the board.

c) Disconnect the power switch cable and front I/O cable from the board.

1.3 Remove the PCI shield (see Figure 9&10)

a) Loose the screw that secure PCI card with chassis

b) Remove the metal baffle
1.4 Remove the system fan. (see Figure 11&12 below)
   a) Remove the cables from mainboard.
   b) Loose the screws and remove the system fan from chassis.

1.5 Remove the processor from the system board: (see Figure 13-17 below)
   a) Remove the processor fan cable from the board
   b) Loosen the screws that secures the CPU fan to the system board.
   c) Lift the heat sink from atop the processor and set it on its side to keep from contaminating the work area with thermal grease.
   d) Rotate the handle and lift the processor from the socket.

1.6 Remove the Memery. (see Figure 18&19 below)
   a) push the two handles of the DIMM slot
   b) Lift the memery from the DIMM slot

1.7 Remove the system board: (see Figure 20&21 below)
   a) Remove the screws that secure the system board to the chassis.
   b) Lift the system board towards then remove it.

2. BATTERY

2.1 Release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. Then the battery pops up, lift it out. (see Figure 22 below).

3. SYSTEM DRIVERS

3.1 Remove the HDD. (see Figure 23-29 below)
   a) Remove the cables connect to the HDD.
   b) Loose the screws that secure the HDD cage to chassis
   c) Push the handle and push the HDD cage off the chassis
   d) Loose the screws on the two side of the HDD cage
   e) Pull the HDD from the HDD cage

3.2 Remove the ODD. (see Figure 30-33 below)
a) Remove the cables connect to the ODD.

b) Pull outward on all three tabs on the front bezel.

c) Loose the screws on the ODD cage

d) Lift the handle and pull the ODD out of the ODD cage.

3.3 Remove the front I/O.(see Figure 34-36 below)

a) Loose the screw that secure the front I/O to chassis.

b) Cut the plastic cable clamp that secures the cables to the cover

c) Lift the Front I/O and pull it out of the chassis.

3.4 Remove the power on/off switch.(see Figure 37&38 below)

a) Extrusion the bottom of the switch.

b) Pull the switch out of the chassis.

4. POWER SUPPLY

4.1 Take off the power supply: (see Figure 39-42 below)

a) Remove the four screws that secure the power supply to the chassis.

b) Press the baffle and slide the power supply toward the front of the computer,

c) Lift the power supply out of the chassis.

4.2 Remove the cover from the power supply: (see Figures 43-47 below)

a) Remove the six screws that secure the cover to the power supply chassis.

b) Cut the plastic cable clamp that secures the cables to the cover.

c) Lift the cover off the power supply.

d) Cut the plastic cable clamp that secures the cables to the power cable.

e) Remove the four screws of the PFC module.

f) Lift the PFC out of the power supply cage.

4.3 Remove the power supply fan (see Figures 48&49)

a) Remove the four screws on the power supply

b) Lift the power supply fan from the cage.
4.4 Remove the power supply PCA: (see Figure 50-54 below)

a) Remove the screw that secure the ground to the cage.

b) Remove the screw that secure the switch to the chassis

c) Push the switch and light out of the cage.

d) Remove the four screws that secure the power supply PCA to the chassis.

e) Remove the power supply PCA from the power supply chassis.

4.4 Remove the Electrolytic Capacitors:(see Figure 55&56 below)

a) Using Soldering Iron, heat the solder of Electrolytic Capacitors.

b) Remove the Electrolytic Capacitors.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the screw of the cover

Figure 2 Pull out the chassis cover

Figure 3 Disconnect the cables from the board

Figure 4 Disconnect the cables from the board

Figure 5 Disconnect the cables from the board

Figure 6 Disconnect the cables from the board
Figure 7 Disconnect the cables from the board

Figure 8 Disconnect the cables from the board

Figure 9 Loose the screw of PCI shielding

Figure 10 Remove the PCI shield

Figure 11 Disconnect the system fan from the board

Figure 12 Loose the four screws and remove the fan

PSG instructions for this template are available at EL-MF877-01
Figure 13 Remove the CPU fan cable from the board

Figure 14 Put up the CPU fan handle

Figure 15 Remove the CPU fan

Figure 16 Rotate the handle and open it up

Figure 17 Remove the processor from the socket.

Figure 18 Push the two handles of the DIMM slot
Figure 19 Lift the memory from the DIMM slot

Figure 20 Loose the screws on the board

Figure 21 Pull and lift the MB out of the chassis

Figure 22 Remove the battery from system board

Figure 23 Remove the cables connect to the HDD

Figure 24. Loose the screws on the HDD cage
<table>
<thead>
<tr>
<th>Figure 25</th>
<th>Push the handle of the HDD cage</th>
</tr>
</thead>
<tbody>
<tr>
<td>Figure 26</td>
<td>Pull the HDD cage off the chassis</td>
</tr>
<tr>
<td>Figure 27</td>
<td>Loose the screws on the side of HDD cage</td>
</tr>
<tr>
<td>Figure 28</td>
<td>Loose the screws on other side of HDD cage</td>
</tr>
<tr>
<td>Figure 29</td>
<td>Pull the HDD from the HDD cage</td>
</tr>
<tr>
<td>Figure 30</td>
<td>Remove the cables connect to the ODD</td>
</tr>
<tr>
<td>Figure</td>
<td>Instruction</td>
</tr>
<tr>
<td>--------</td>
<td>-------------</td>
</tr>
<tr>
<td>Figure 31</td>
<td>Pull the switch tabs on the front bezel</td>
</tr>
<tr>
<td>Figure 32</td>
<td>Loose the screws on the ODD cage</td>
</tr>
<tr>
<td>Figure 33</td>
<td>Pull the ODD out of the ODD cage</td>
</tr>
<tr>
<td>Figure 34</td>
<td>Loose the screw of the front I/O to chassis.</td>
</tr>
<tr>
<td>Figure 35</td>
<td>Cut the plastic cable clamp</td>
</tr>
<tr>
<td>Figure 36</td>
<td>Lift the Front I/O and pull it out</td>
</tr>
</tbody>
</table>
Figure 37 Remove the switch cable out of the slot

Figure 38 Extrusion the bottom of the power on/off switch and Pull it out of the chassis

Figure 39 Remove four screws on the power supply

Figure 40 Press the baffle and slide the PSU

Figure 41 Lift the power supply out of the chassis.

Figure 42 Remove six screws on the power supply

PSG instructions for this template are available at EL-MF877-01
Figure 43 Cut the outside plastic cable clamp

Figure 44 Lift the cover off the power supply.

Figure 45 Cut the inside plastic cable clamp

Figure 46 Remove four screws of the PFC module.

Figure 47 Lift the PFC out of the power supply cage

Figure 48 Remove the four screws on the PSU

PSG instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Figure 49</th>
<th>Lift the power supply fan from the cage.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Figure 50</td>
<td>Remove the screw on the ground cable</td>
</tr>
<tr>
<td>Figure 51</td>
<td>Remove the screw on the connector and switch</td>
</tr>
<tr>
<td>Figure 52</td>
<td>Push the switch and light out of the cage.</td>
</tr>
<tr>
<td>Figure 53</td>
<td>Remove four screws on the PCA board</td>
</tr>
<tr>
<td>Figure 54</td>
<td>Remove the PCA out of the cage.</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 55 Heat the solder of Electrolytic Capacitors.

Figure 56 Remove the Electrolytic Capacitors.